

### Abstract of the Disclosure

A semiconductor integrated circuit device comprises a semiconductor substrate squared in plane surface, a plurality of pads disposed over a main surface of the semiconductor substrate along one side of the semiconductor substrate, a plurality of input/output cells disposed corresponding to the plural pads over the main surface of the semiconductor substrate, an internal circuit forming section disposed over the main surface of the semiconductor substrate and inner than the plural input/output cells, and power supply wirings for internal circuit, for supplying potentials to the internal circuit forming section, which are respectively disposed inner than the plural input/output cells. The plural input/output cells include signal cells and power supply cells for internal circuit respectively. The plural pads include signal pads respectively disposed corresponding to the signal cells and electrically connected the signal cells, and power supply pads for internal circuit respectively disposed corresponding to the power supply cells and electrically connected to the power supply cells and the power supply wirings. The power supply pads are disposed closer to the power supply wirings than the signal pads.